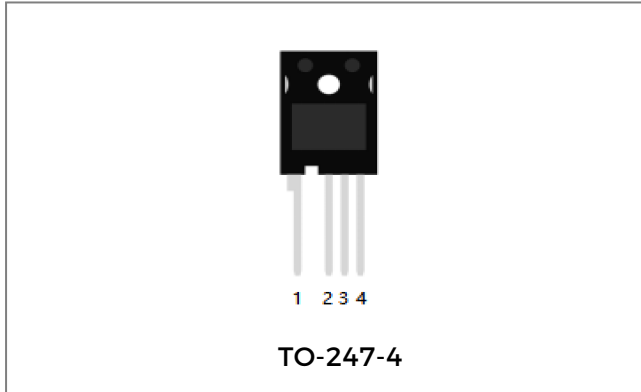


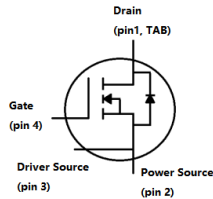
S4M0019170K Silicon Carbide Power MOSFET



Features

- Positive temperature characteristics, easy to parallel.
- Low on-resistance typ. $R_{DS(on)} = 19 \text{ m}\Omega$.
- Fast switching speed and low switching losses.
- Very fast and robust intrinsic body diode.
- Process of non-bright tin electroplatin.
- "-A" is an AEC-Q101 qualified device.

Circuit Diagram



Applications

- EV Fast Charging Modules
- EV On Board Chargers
- Solar Inverters
- Online UPS/Industrial UPS
- SMPS (Switch Mode Power Supplies)
- DC-DC Converters
- ESS (Energy Storage Systems)

Maximum Ratings($T_c = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Units	Note
Drain - Source Voltage	V_{DSmax}	$V_{GS} = 0 \text{ V}$, $I_D = 100 \mu\text{A}$			1700	V	
Gate - Source Voltage (dynamic)	V_{GSmax}	AC ($f > 1 \text{ Hz}$)	-8		+22	V	
Gate - Source Voltage (static)	V_{GSop}	Static		-4 / +18		V	[1]
Continuous Drain Current	I_D	$V_{GS} = 18 \text{ V}$, $T_c = 25^\circ\text{C}$ $V_{GS} = 18 \text{ V}$, $T_c = 100^\circ\text{C}$			107 76	A	
Pulsed Drain Current	$I_{D(pulse)}$	Pulse width t_p limited by T_{jmax}			159	A	
Power Dissipation	P_D	$T_c = 25^\circ\text{C}$			685	W	

[1] Recommended turn off gate voltage is -4 V. Recommended turn on gate voltage is 18 V. Do not use with $V_{GSON} < 12 \text{ V}$.

Electrical Characteristics:

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Units
Drain Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0 \text{ V}, I_D = 100 \mu \text{ A}$	1700			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 25 \text{ mA}$	2	3.1	4	V
		$V_{DS} = V_{GS}, I_D = 25 \text{ mA}, T_J = 175^\circ \text{ C}$		2.2		V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 1700 \text{ V}, V_{GS} = 0 \text{ V}$		1	100	$\mu \text{ A}$
Gate Source Leakage Current	I_{GSS}	$V_{GS} = 18 \text{ V}, V_{DS} = 0 \text{ V}$		10	250	nA
Drain Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 18 \text{ V}, I_D = 75 \text{ A}$	13	19	25	m Ω
		$V_{GS} = 18 \text{ V}, I_D = 75 \text{ A}, T_J = 175^\circ \text{ C}$		38		m Ω
Transconductance	g_{fs}	$V_{DS} = 20 \text{ V}, I_{DS} = 75 \text{ A}$		26		S
		$V_{DS} = 20 \text{ V}, I_{DS} = 75 \text{ A}, T_J = 175^\circ \text{ C}$		5		S
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}$		4071		pF
Output Capacitance	C_{oss}	$V_{DS} = 1700 \text{ V}$		172		
Reverse Transfer Capacitance	C_{rss}	$V_{AC} = 25 \text{ mV}$		7		
COSS Stored Energy	E_{oss}	$f = 100 \text{ kHz}$		273		$\mu \text{ J}$
Turn-On Switching Energy	E_{on}	$V_{DS} = 1000 \text{ V}, V_{GS} = -4 / 18 \text{ V}$		736		$\mu \text{ J}$
Turn-Off Switching Energy	E_{off}	$I_D = 75 \text{ A}, R_{G(ext)} = 2.5 \Omega, L = 99 \mu \text{ H}$		309		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS} = 1000 \text{ V}, V_{GS} = -4 / 18 \text{ V}$		17		ns
Rise Time	t_r	$I_D = 75 \text{ A}, R_{G(ext)} = 2.5 \Omega$		20		
Turn-Off Delay Time	$t_{d(off)}$	Inductive Load Timing relative to		31		
Fall Time	t_f	V_{DS} Per IEC60747-8-4 pg 83		8		
Internal Gate Resistance	$R_{G(int)}$	$f = 1 \text{ MHz}, AC = 25 \text{ mV}$		1.8		Ω
Gate to Source Charge	Q_{gs}	$V_{DS} = 1000 \text{ V}, V_{GS} = -4 / 18 \text{ V}$		38		nC
Gate to Drain Charge	Q_{gd}	$I_D = 75 \text{ A}$		35		
Total Gate Charge	Q_g	Per IEC60747-8-4 pg 21		166		

Reverse Diode Characteristics (TA = 25 °C, unless otherwise specified)

Characteristics	Symbol	Conditions	Typ.	Max.	Units
Diode Forward Voltage	V _{SD}	V _{GS} = -4 V, I _{SD} = 37.5 A	3.9		V
	V _{SD}	V _{GS} = -4 V, I _{SD} = 37.5 A, T _J = 175 °C	3.4		V
Reverse Recovery Time	t _{rr}	V _{GS} = -4 V, I _{SD} = 75 A, T _J = 25 °C	24		ns
Reverse Recovery Charge	Q _{rr}	V _R = 1000 V	379		nC
Peak Reverse Recovery Current	I _{RRM}	dif / dt = 2000 A / μs	29		A

Thermal-Mechanical Specifications

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T _J	-	-55 to +175	°C
Storage Temperature	T _{stg}	-	-55 to +175	°C
Typical Thermal Resistance Junction to Case	R _{θ JC}	DC operation	0.22	°C /W

Ordering Information

Device	Package	Shipping
S4M0019170K	TO-247-4	30 pcs/tube

Marking Diagram



Where XXXXX is YYWWL

S4M = Device Type
 0019 = RDS(on)
 170 = Reverse Voltage (1700V)
 K = Package
 SSG = SSG
 YY = Year
 WW = Week
 L = Lot Number

Cautions: Molding resin
 Epoxy resin UL94V-0

Ratings and Characteristics Curves

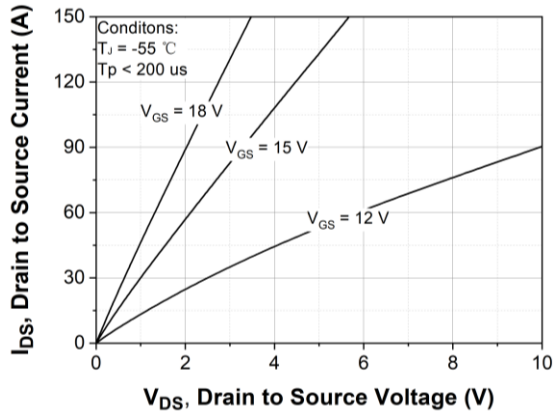


Figure 1. Output Characteristics $T_J = -55^\circ\text{C}$

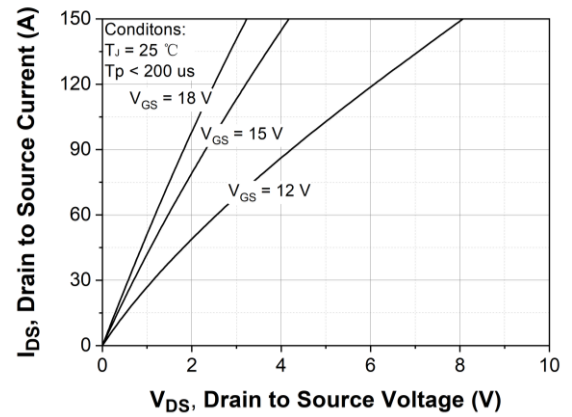


Figure 2. Output Characteristics $T_J = 25^\circ\text{C}$

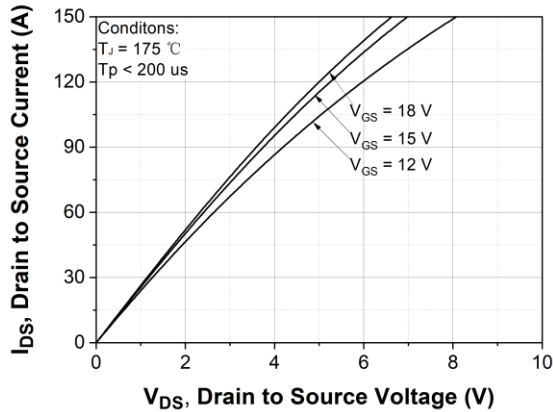


Figure 3. Output Characteristics $T_J = 175^\circ\text{C}$

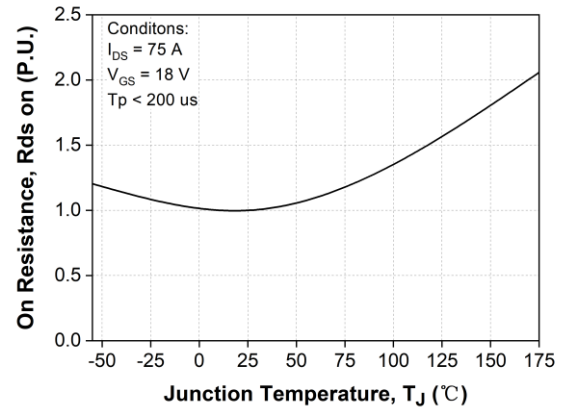


Figure 4. Normalized On-Resistance vs. Temperature

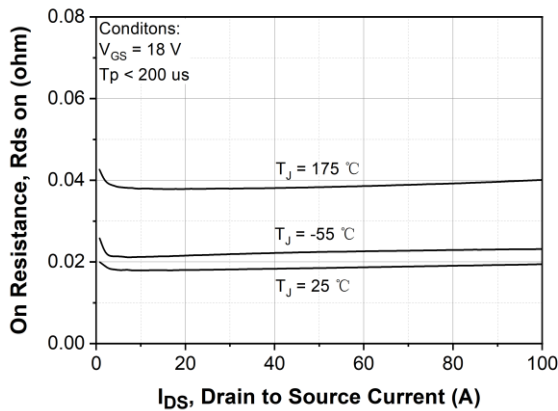


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

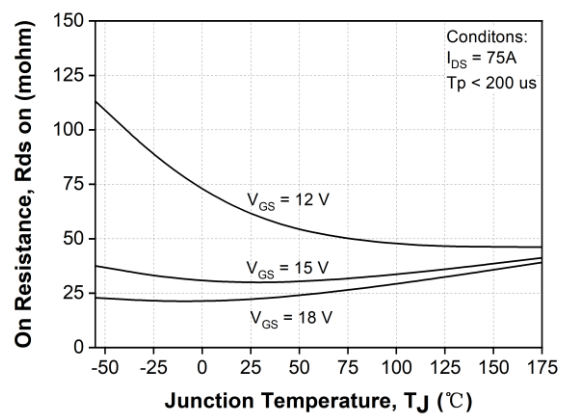


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage

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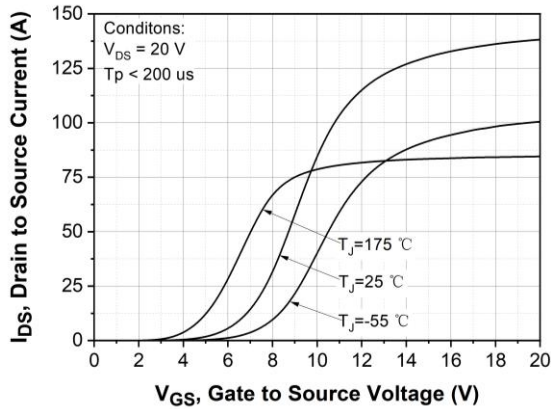


Figure 7. Transfer Characteristic for Various Junction Temperatures

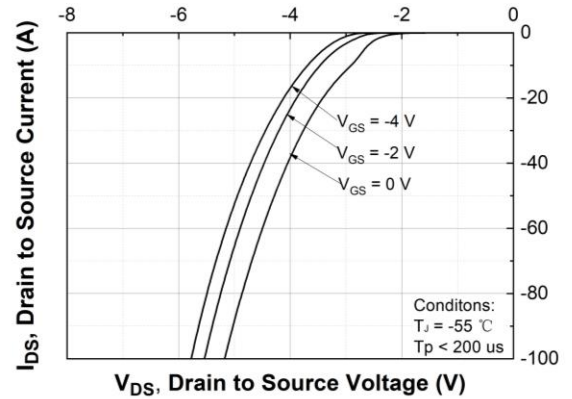


Figure 8. Body Diode Characteristic at $T_J = -55\text{ }^{\circ}\text{C}$

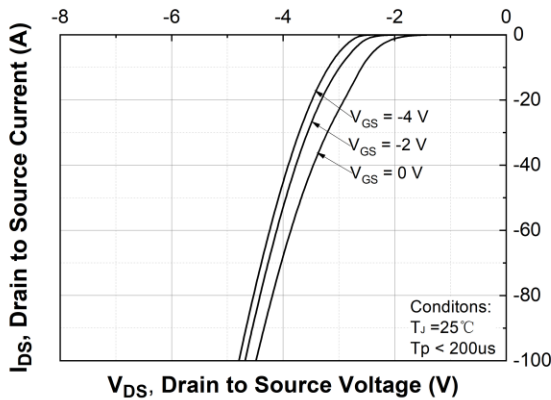


Figure 9. Body Diode Characteristic at $T_J = 25\text{ }^{\circ}\text{C}$

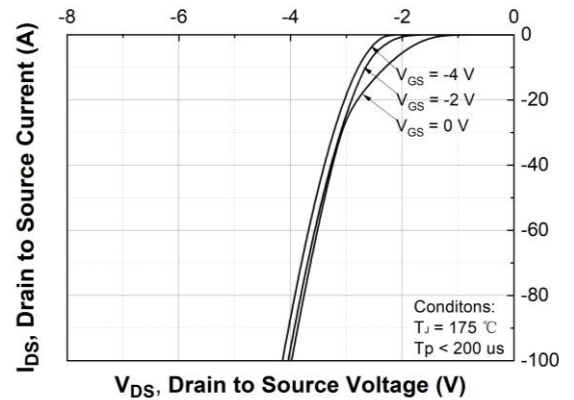


Figure 10. Body Diode Characteristic at $T_J = 175\text{ }^{\circ}\text{C}$

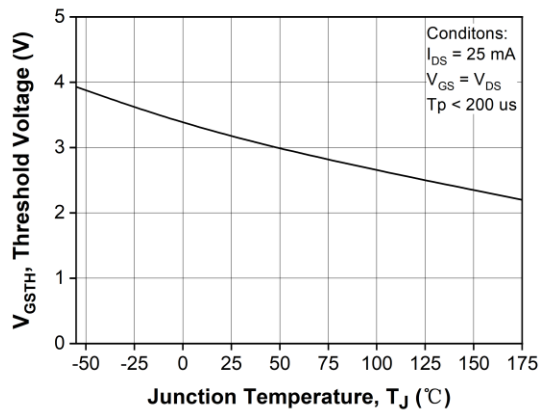


Figure 11. Threshold Voltage vs. Temperature

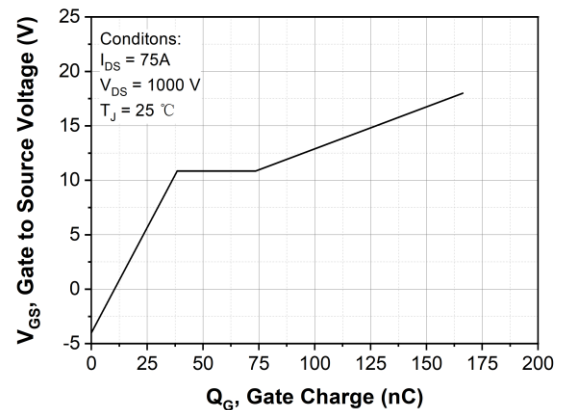


Figure 12. Gate Charge Characteristic

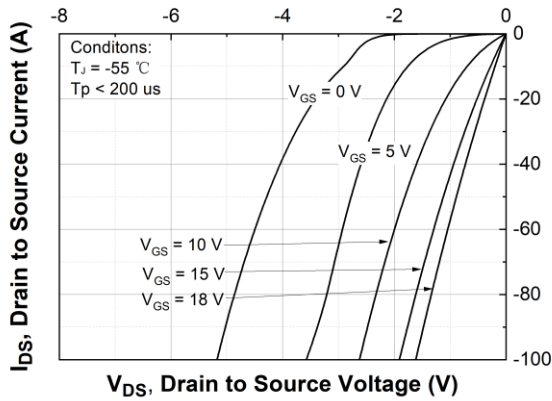


Figure 13. 3rd Quadrant Characteristic at $T_J = -55\text{ }^{\circ}\text{C}$

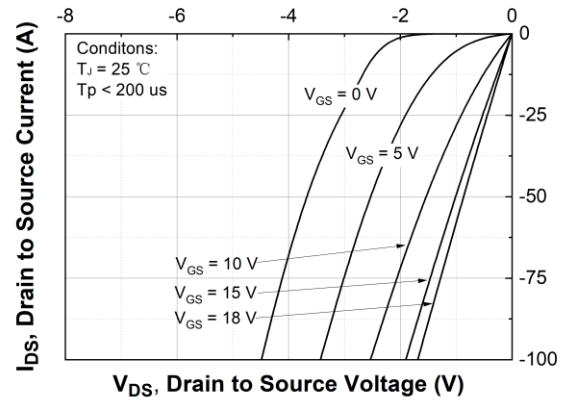


Figure 14. 3rd Quadrant Characteristic at $T_J = 25\text{ }^{\circ}\text{C}$

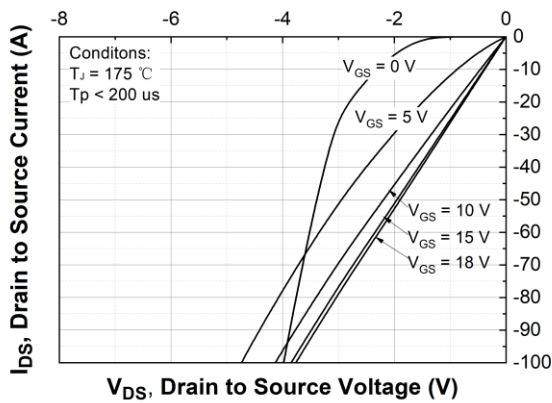


Figure 15. 3rd Quadrant Characteristic at $T_J = 175\text{ }^{\circ}\text{C}$

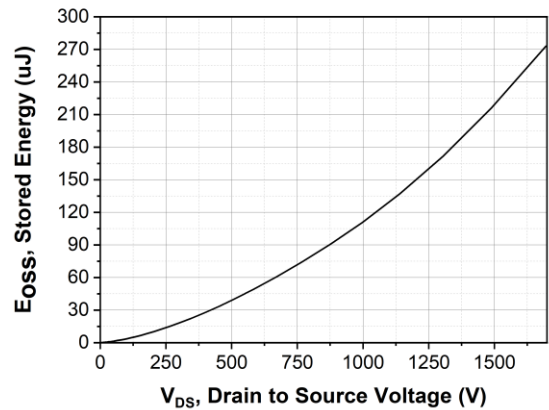


Figure 16. Output Capacitor Stored Energy

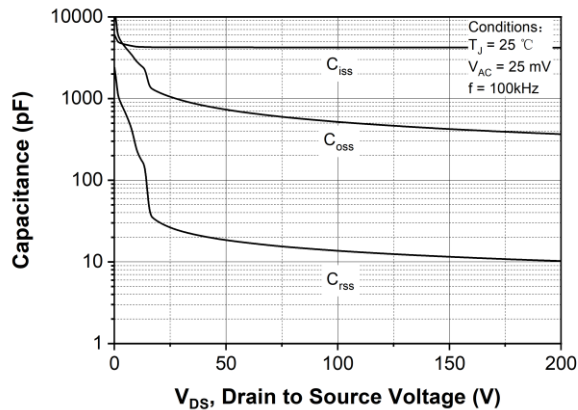


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200 V)

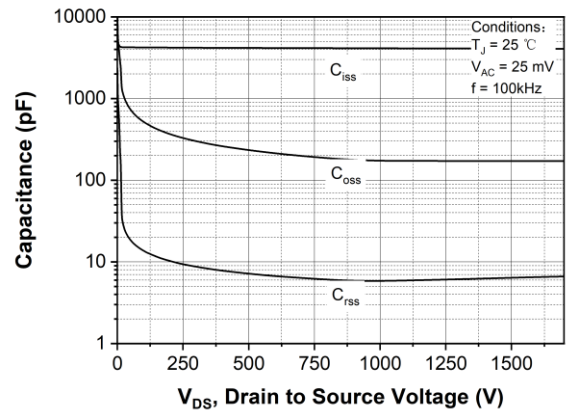


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1700 V)

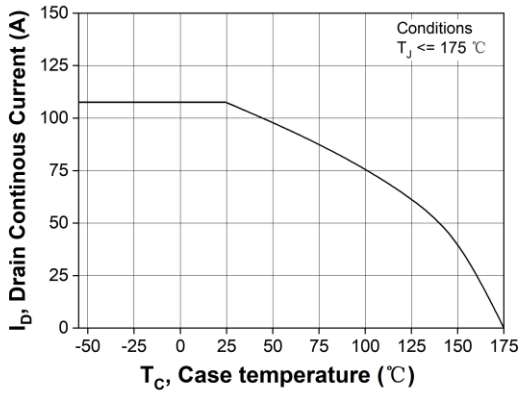


Figure 19. Continuous Drain Current Derating vs. Case Temperature

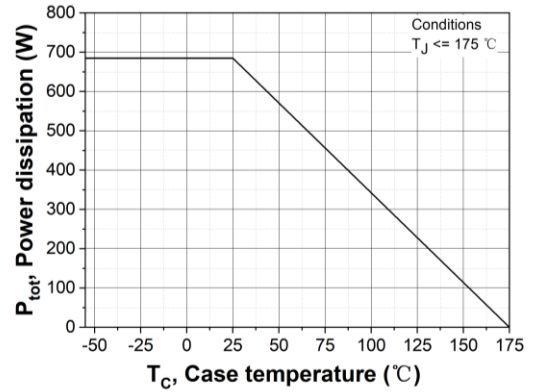


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

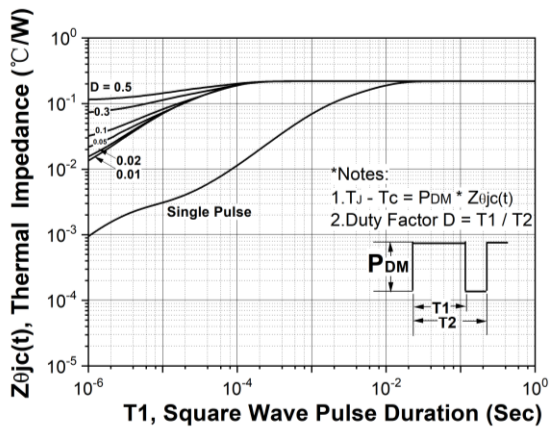


Figure 21. Transient Thermal Impedance (Junction - Case)

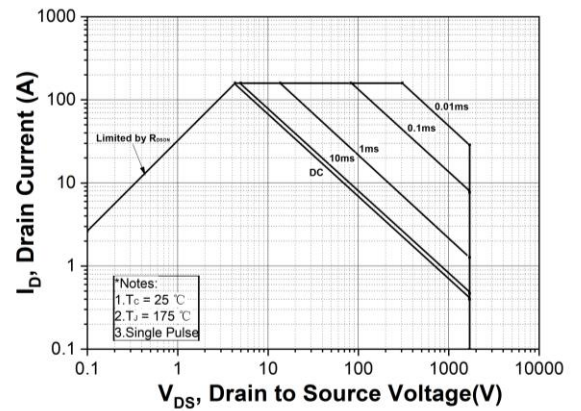


Figure 22. Safe Operating Area

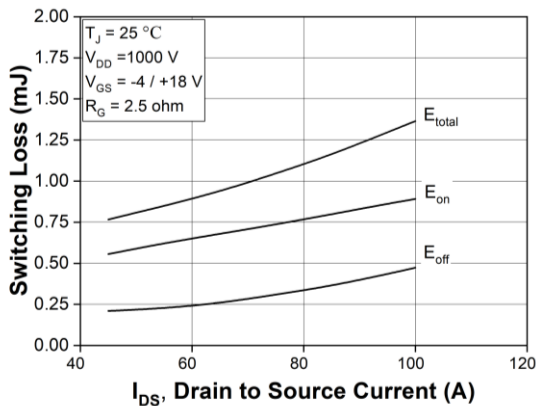


Figure 23. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 1000V$)

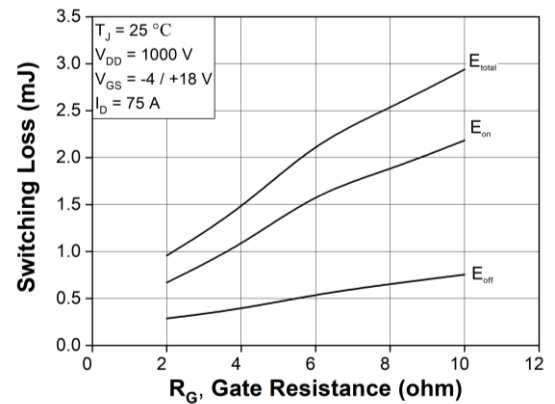


Figure 24. Clamped Inductive Switching Energy vs. $R_{G(ext)}$

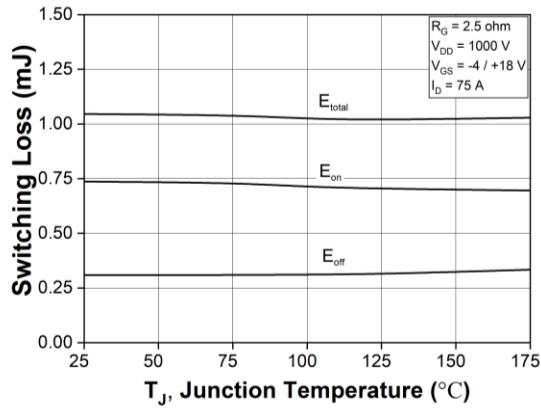


Figure 25. Clamped Inductive Switching Energy vs. Temperature

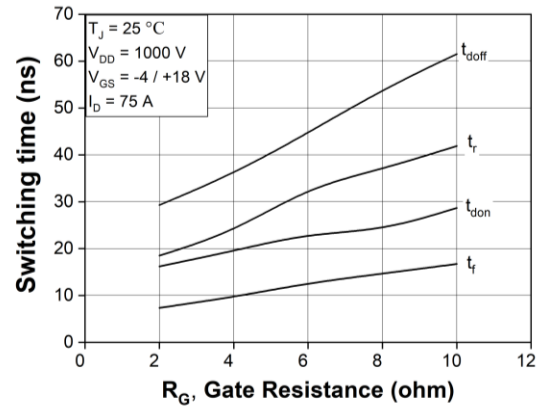
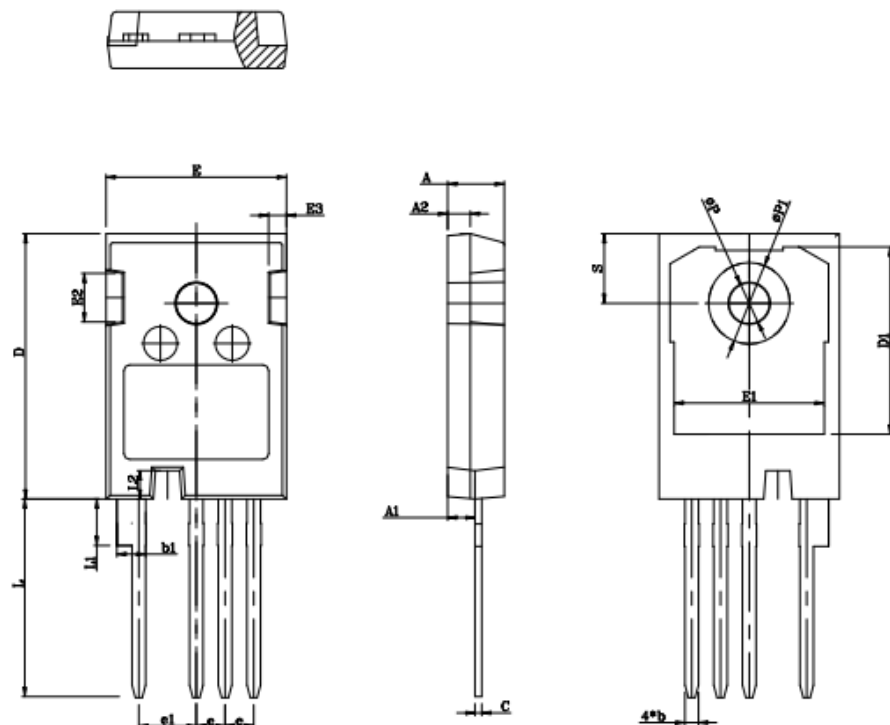


Figure 26. Switching Times vs. R_{G(ext)}

Mechanical Dimensions TO-247-4



COMMON DIMENSIONS

SYMBOL	mm		
	Min	Nom	Max
A	4.80	5.00	5.20
A1	2.23	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b1	2.35	2.55	2.75
c	0.51	0.61	0.75
D	23.30	23.45	23.60
D1	16.25	16.55	16.85
E	15.75	15.94	16.10
E1	13.00	13.26	13.43
E2	4.00	4.30	4.60
E3	1.15	1.45	1.75
e	2.54BSC		
e1	5.08BSC		
L	17.31	17.47	17.82
L1	1.50	4.12	4.30
L2	2.35	2.5	2.65
ØP	3.55	3.65	3.75
ØP1	7.08	7.19	7.30
S	6.15BSC		

The outline from different package houses may have slight differences. So the outline above is just schematic. The dimensions are controlled per specifications.

Technical Data

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